

Patent claims

1. An integrated circuit arrangement (1) comprising a  
5 nonplanar substrate (2) on which an integrated circuit  
is formed on at least one side,  
characterized in that  
that side (3) of the substrate (2) which has the  
integrated circuit is arranged on a carrier (4) and the  
10 carrier (4) is produced from a chemically resistant  
material.
2. The integrated circuit arrangement (1) as claimed  
in claim 1,  
15 characterized in that  
the chemically resistant material of the carrier (4) is  
formed from ceramic.
3. The integrated circuit arrangement (1) as claimed  
20 in claim 1 or 2,  
characterized in that  
the carrier (4) has a planar surface on a side (6)  
which is remote from the integrated circuit.
- 25 4. The integrated circuit arrangement (1) as claimed  
in one of claims 1 to 3,  
characterized in that  
the substrate (2) is connected to the carrier (4) over  
the entire area.
- 30 5. The integrated circuit arrangement (1) as claimed  
in one of claims 1 to 4,  
characterized in that  
the carrier (4) has a cavity (5) in which the substrate  
35 (2) is completely held.